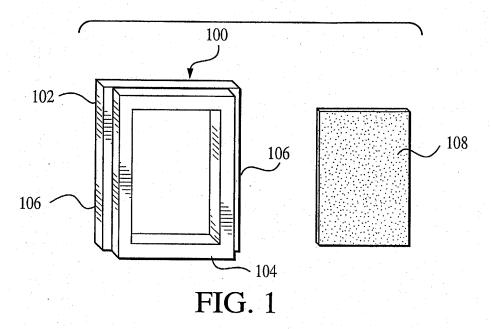
Inventors: Sullivan, et al.
Title: High Density 3-D Integrated Circuit Package
Attorney: Dennis Bremer
Attorney Docket No: A11-26110US



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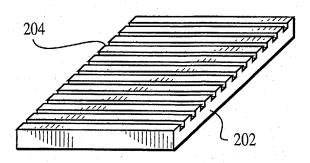
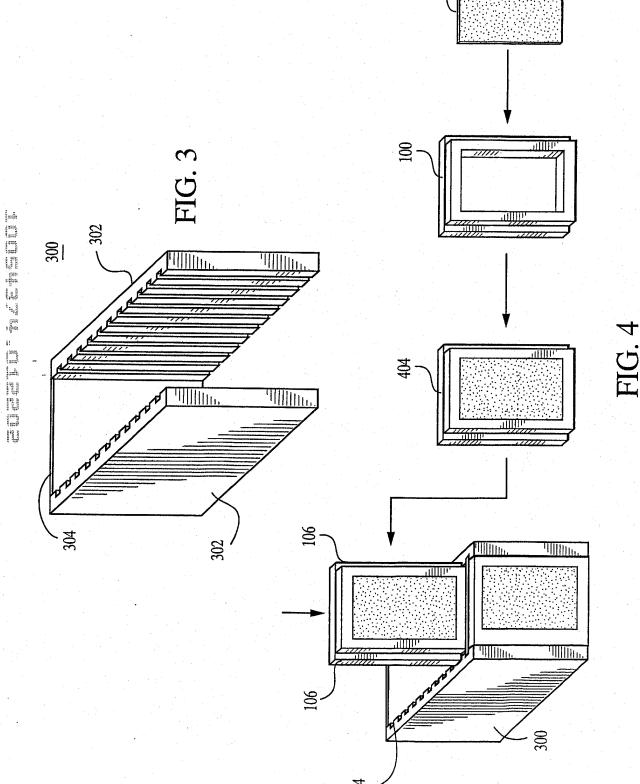


FIG. 2

Inventors: Sullivan, et al.
Title: High Density 3-D Integrated Circuit Package
Attorney: Dennis Bremer
Attorney Docket No: A11-26110US Sheet 2 of 3 2/3 الاللار יווווו '||||||



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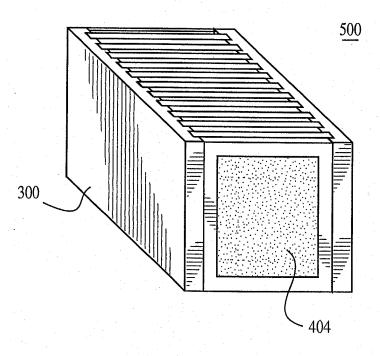


FIG. 5